

苏州东微半导体股份有限公司涉及豁免物质

Substance	CAS NO.	PPM level	Affected Material	Description of Use	Involving products
铅#Lead	231-100-4 /7439-92-1	2866~8728PPM RoHS 2011/65/EU 豁免项第 7 (a)	Solder	Die Bond	

